Product-Env-Stewards     Product Enviro Compliance     NA     Product-Env-Stewards@onsemi.com       Requester Item Number     Mfr Item Number     Mfr Item Name     Effective Date     Version     Manufacturing Site     Weight*     UOM     U	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name*  Company name*  Company unique ID  Unique ID Authority  Response Date*  2023-06-08  Contact Name  Title - Contact  Title - Contact  Phone - Contact*  Phone - Contact*  Phone - Contact*  Email - Contact*  Email - Contact*  Product-Env-Stewards  Outhorized Representative*  Title - Representative  Title - Representative  Phone - Representative*  Product-Env-Stewards  Outhorized Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Version  Manufacturing Site  Weight*  Version  Manufacturing Site  Weight*  UoM  Version  Manufacturing Site  Weight*  Version  Manufact	752-21.1										als and Mfg	Informatio	on		
Semil	upplier Informa	ntion				•		·							
Title - Contact Name Product Envi-Stewards	Company name* Company unique ID					Unique ID Authority				Response Date*					
Product-Env-Stewards	nsemi											2023-06-08	1		
Authorized Representative*  Product-Env-Stewards  Requester Item Number  Mfr Item Number  M	ontact Name			Title - Conta	ct		1	Phone - Conta	ct*			Email - Co	ntact*		
Product Envi-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  NCV303LSN28TIG  2.8V ANA UNDERVOLT DETECT  2023-06-08  MY1  14.08  mg  I  Manufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Matte Tin (Sn) - annealed  CU Alloy  I  And Time at Peak Temperature  Number of Reflow Cycles  Seconds  And Tomperature  Number of Reflow Cycles  Seconds  Comments	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*			
NCV303LSN28T1G   2.8V ANA UNDERVOLT DETECT   2023-06-08   MY1   14.08   mg   I	Product-Env-Stewards Pr				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Anufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site	We	ight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			NCV303I	LSN28T1G	2.8V ANA UNDE	RVOLT DETE	ECT	2023-06-08		N	ЛY1	14.	08	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments				amainal Dasa	Allow	CTD 020 MCI	I. Dotino	Dools Droo	aga Dady T	·	May Time at Peak	Tomoromotore	Numbe	on of Dofloys Cyc	Jac
Comments					Alloy J-	S I D-020 MSI	L Kating		ess Body 1	T *				er of Reflow Cyc	ies
	•	(Sn) - annealed	C	U Alloy	1			200		JC	30	seconds	]3		
ver r - maximum time at deak temberature during soldering is 10-30 seconds			Ji	J	20										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.42	mg	Supplier	Silicon (Si)	7440-21-3		0.42	mg
Die Attach	0.11	mg	Supplier	Silver (Ag)	7440-22-4		0.088	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.022	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0069	mg
			Supplier	Iron (Fe)	7439-89-6		0.1358	mg
			Supplier	Copper (Cu)	7440-50-8		5.565	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.04	mg	Supplier	Gold (Au)	7440-57-5		0.04	mg